

SN74CBTLV1G125 LOW-VOLTAGE SINGLE FET BUS SWITCH

SCDS057G – MARCH 1998 – REVISED OCTOBER 2003

- 5- Ω Switch Connection Between Two Ports
- Rail-to-Rail Switching on Data I/O Ports
- I_{off} Supports Partial-Power-Down Mode Operation

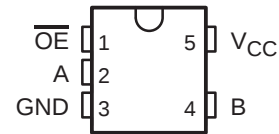
description/ordering information

The SN74CBTLV1G125 features a single high-speed line switch. The switch is disabled when the output-enable ($\overline{OE}$) input is high.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DBV OR DCK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]
-40°C to 85°C	SOT (SOT-23) – DBV	Tape and reel	SN74CBTLV1G125DBVR	V25_
	SOT (SC-70) – DCK	Tape and reel	SN74CBTLV1G125DCKR	VM_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡] The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

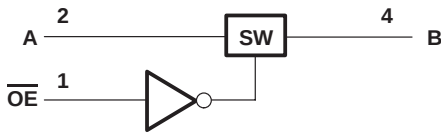
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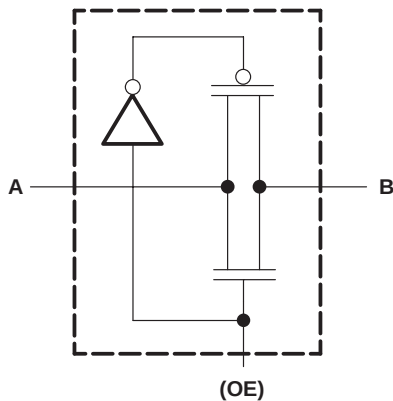
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logic diagram (positive logic)



simplified schematic, each FET switch



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 4.6 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2	
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	V
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	0.8	
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
V _{IK}		V _{CC} = 3 V,	I _I = −18 mA			−1.2	V	
I _I		V _{CC} = 3.6 V,	V _I = V _{CC} or GND			±1	μA	
I _{off}		V _{CC} = 0,	V _I or V _O = 0 to 3.6 V			10	μA	
I _{CC}		V _{CC} = 3.6 V,	I _O = 0, V _I = V _{CC} or GND			10	μA	
ΔI _{CC} [‡]	Control inputs	V _{CC} = 3.6 V,	One input at 3 V, Other inputs at V _{CC} or GND			300	μA	
C _i	Control inputs	V _I = 3 V or 0				2.5	pF	
C _{io(OFF)}		V _O = 3 V or 0,	$\overline{OE}$ = V _{CC}			7	pF	
r _{on} [§]		V _{CC} = 2.3 V, TYP at V _{CC} = 2.5 V	V _I = 0	I _I = 64 mA		7	10	Ω
				I _I = 24 mA		7	10	
			V _I = 1.7 V,	I _I = 15 mA		15	25	
		V _{CC} = 3 V	V _I = 0	I _I = 64 mA		5	7	
				I _I = 24 mA		5	7	
			V _I = 2.4 V,	I _I = 15 mA		10	15	

[†] All typical values are at $V_{CC} = 3.3\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

[‡] This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\parallel}$	A or B	B or A		0.15		0.25	ns
t_{en}	$\overline{OE}$	A or B	1	4	1	4	ns
t_{dis}	$\overline{OE}$	A or B	1	5	1	4.1	ns

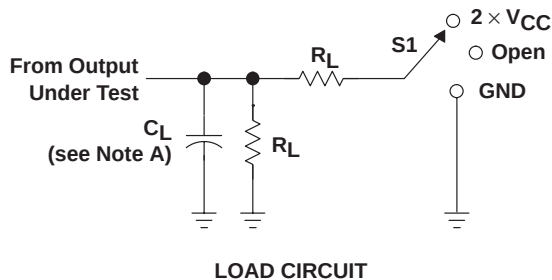
^{||} The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF , when driven by an ideal voltage source (zero output impedance).

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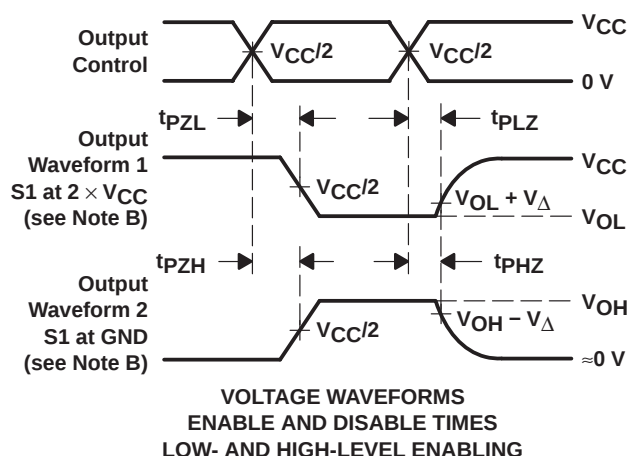
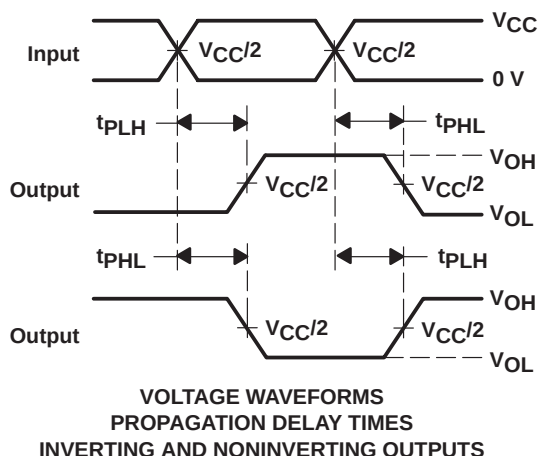
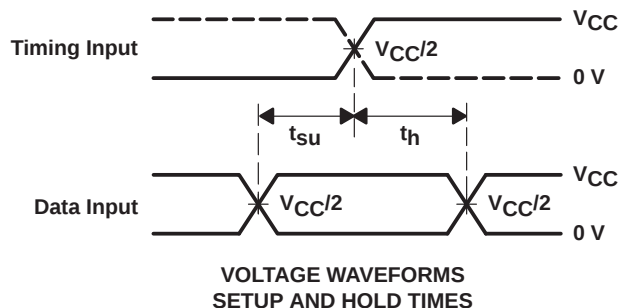
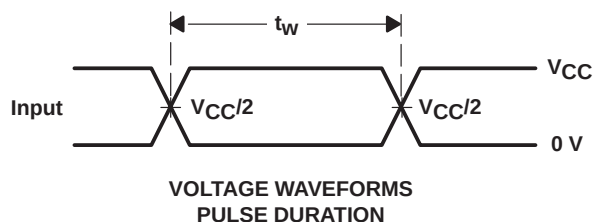
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PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

V_{CC}	C_L	R_L	V_{Δ}
$2.5 \text{ V} \pm 0.2 \text{ V}$	30 pF	500 Ω	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	50 pF	500 Ω	0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74CBTLV1G125CRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTLV1G125CRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBTLV1G125DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTLV1G125DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBTLV1G125DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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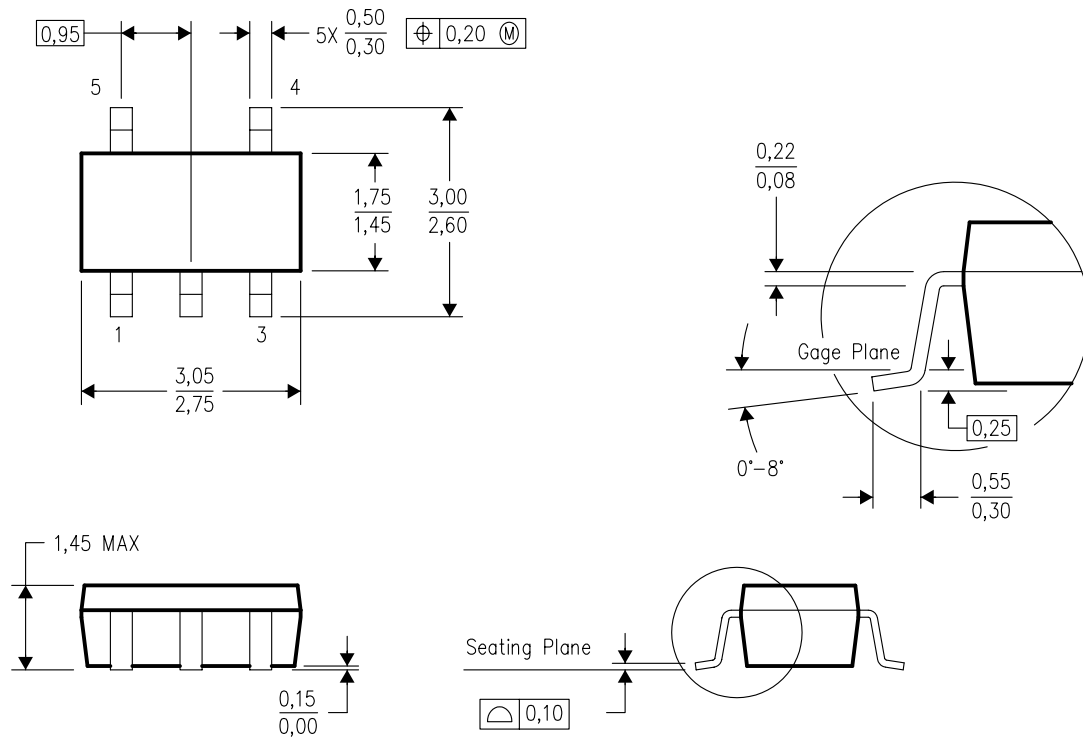
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

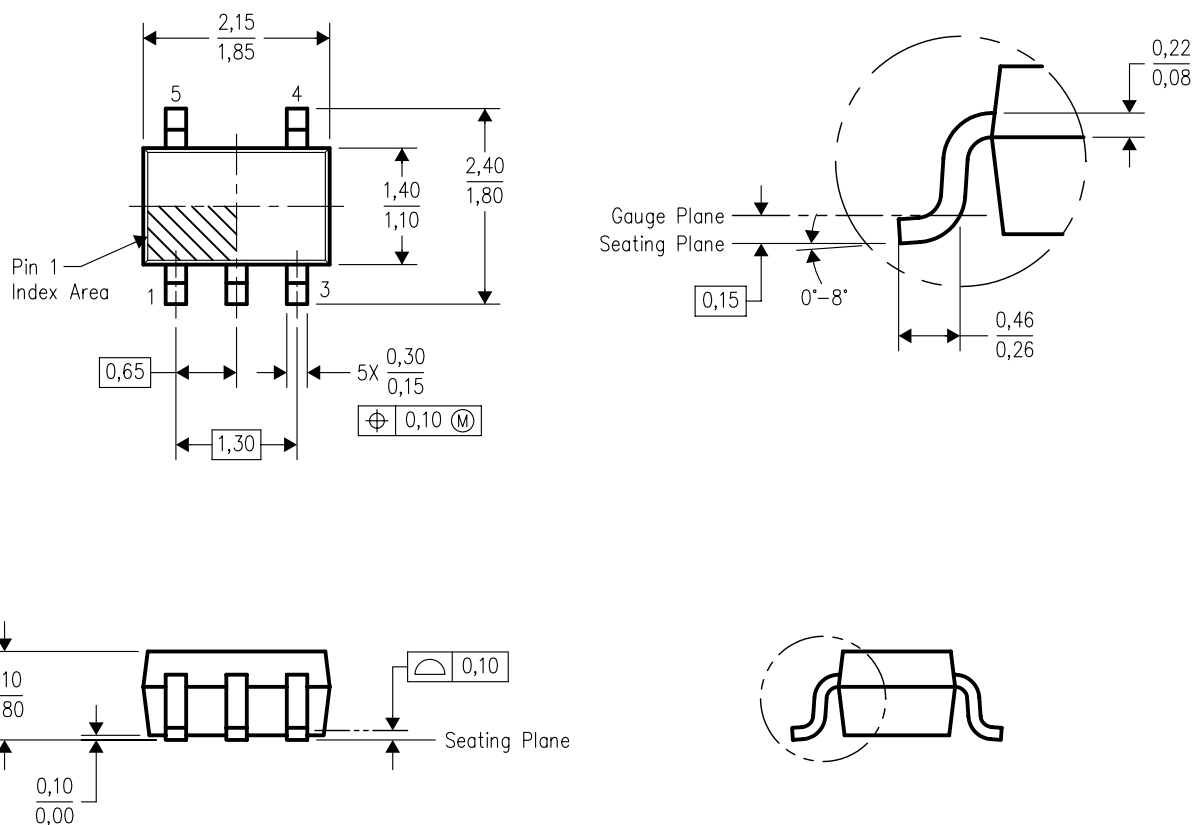


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- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



4093553-2/E 10/2005

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - Falls within JEDEC MO-203 variation AA.

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